















www.mcnex.com

















COMPANY NAME	MCNEX Co., Ltd.	REVENUE	USD 1.0B in 2024
HEADQUARTER	Incheon, South Korea	IPO	Listed on Korean exchange market (KOSPI) in 2023
MAIN FACTORY	Ninh Binh, Vietnam	CERTIFIED	IATF 16949 IN 2018
ESTABLISHED	Dec. 2004		

MAIN CUSTOMER































AUTOMOTIVE SOLUTION

Multi interface camera module	Shark Antenna camera system	Dual scanning camera
AHD, LVDS(GMSL, FPD-link), Ethernet, etc.	In-cabin camera system: DMS, OMS	High resolution camera: 7.4MP, 8MP
ADAS & Autonomous driving camera applications	FRU (Face Recognition unit) system	Fingerprint sensing system
SVM, MFC, Tri-focal camera system, Dual camera, etc.	DVRS system: FHD, QHD	ToF camera

MOBILE SOLUTION

SMART PHONE CAMERA MODULE	ACTUATOR	BIOMETRIC MODULE
Single, Dual, Triple, Quadruple camera	VCM, Encoder, OIS	Iris, Face recognition camera
OIS, Folded zoom, ToF camera	Folded zoom	Fingerprint & Body temp. Sensing module. Skin sensor module

SYSTEM SOLUTION

Dashcam, Golf range finder, Network Camera, Medical camera, AR/VR/MR camera, USB camera

EMS (ELECTRONICS MANUFACTURING SERVICE)

Manufacturing service for all kinds of electronics items



MULTIMEDIA CORE OF THE NEXT. MONEX

MCNEX IS EXPANDING ITS **GLOBAL NETWORK**ALL OVER THE WORLD







SOUTH KOREA. HEADQUARTER. MCNEX TOWER

NINHBINH. VIETNAM FACTORY I.II. III.IV

SOUTH KOREA . HEADQUARTER

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VIETNAM MAIN FACTORY I.II. III.IV

Lot CN1, Phuc Son Industrial Park, Ninh Binh City, Ninh Binh Province, Hanoi, VIETNAM Tel: +84-303-883-588 FAX: +84-303-880246

● R&D ● Manufacturing ● Sales ● FAE(Field Application Engineer)



HYUNDRI KIN	PSA PELIGEOT CITROEN	Ō
69 vehicle model	2 vehicle model	1 vehicle model
Mercedes-Benz	STELLANTIS	DOOSAN
1 vehicle model	1 vehicle model	2 vehicle mode

TOTAL 1,041 CAMERA MODELS ANNUAL SHIPPING 6.0 MIL MODULES

1,041 model camera modules development (supplying for all premium vehicles in Hyundai, KIA)

MILITARY VEHICLE















ATEGORY	ITEM	SPECIFICATION
	Resolution	1920 * 1080
	Image Sensor	CMOS FHD SENSOR
	Frame Rate	60fps
CAMERA / ECU	View Angle	H:30° / 60° / 120°
	Output Format	LVDS (PoC)
	Power	DC12V (±2.0V)
	Image Format	RAW Data
	Operating Temp.	-40 ~ +105°C

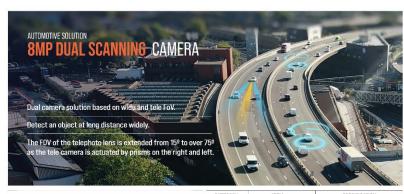








CATEGORY	ITEM	SPECIFICATION
	Input Voltage	DC 7V ~ DC 24V
	FOV	82°
CAMERA	Resolution	1280 * 720P @ 60fps
& ECU	IR	940nm LED
200	Video Output	LVDS (PoC)
	Data Output	CAN
	SENSING	Disparity Map





CATEGURY	IIEM	SPECIFICATION
	Input Voltage	DC 7V ~ DC 24V
	FOV (H)	Wide 120° / Narrow 15°
CAMERA	Resolution	3840 * 2160P
& FCU	Video Output	LVDS (PoC)
200	Data Output	CAN
	SENSING	PD, VD, TLR, TSR



DMS (IR)



CATEGORY	RGB-IR CAMERA	
Sensor	1MEGA(MONO)	
Output Data	POC	
Resolution	1280 x 720p	
IR LED	940nm	
Operating Voltage	DC 12 V ± 0.5 V	

OMS (RGB-IR)



CATEGORY	RGB-IR CAMERA
Sensor	1MEGA(RGB-IR)
Output Data	POC
Resolution	1280 x 720p
IR LED	940nm
Operating Voltage	DC 12 V ± 0.5 V



BUILT IN CAM - 1st GENERATION



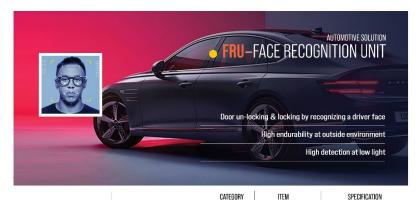
CATEGORY	ITEM	SPECIFICATION
	Image Sensor	FHD CMOS
	Sensor Format	1/2.8 inch
	Resolution	1920 * 1080P @30fps
CAMERA	Pixel Size	2.9um * 2.9μm
	FOV (H)	95°
	F no.	2.0
	Video Output	LVDS, YUV422
	View Mode	Front facing view

BUILT IN CAM - 2st GENERATION



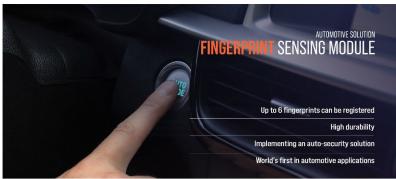


ITEM	FRONT CAMERA	REAR CAMERA
Image Sensor	QHD CMOS	QHD CMOS
Sensor Format	1/1.7 inch	1/1.7 inch
Resolution Driving	2560 *1440P @30fps	2560 *1440P @30fps
Resolution Parking	2560 *1440P @10fps	2560 *1440P @10fps
Pixel Size	2.25µm	2.25µm
FOV(H)	100°	100°
F no.	1.6	1.6
Video Output	POC, RAW 12	POC, RAW 12
View Mode	Built-in front view	Built-in Rear view
G-Sensor	3-axis	140
MIC	Analog Microphone	121
Indicator LED	Blue	Blue











CATEGORY	ITEM	SPECIFICATION
	MCU	32bit RISC CPU
	Max Register no.	6↑
1080000 BOSSN9840V	Interface	SPI
FINGERPRINT SENSING	OS	AUTOSAR
SYSTEM	Communication	CAN, SPI
	FRR/FAR	FRR 1%, FAR 1/100,000
	Operating temp.	-40~85℃
	Touch type	Capacitance





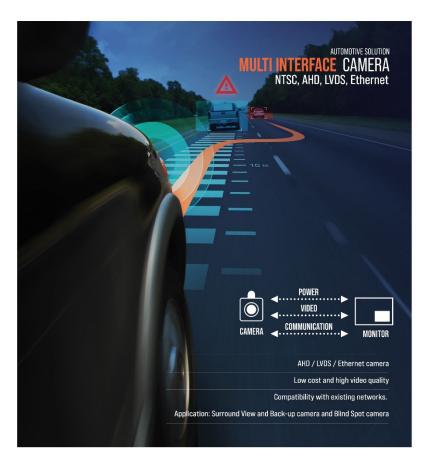


CATEGORY	ITEM	SPECIFICATION
	Input Voltage	DC9V ~ DC25V
CAMERA	Fov(H)	120°
1	Pixel Resolution	7.4/8M pixel
ECU	Video Output	LVDS (POC)
	Data Output	CAN
	SENSING	PD, VD, TLR, TSR





CATEGORY	ITEM	SPECIFICATION	
	Resolution	1280(H) X 800(V), 1Mp	
	Image Sensor	1/4" CMOS Mono	
	Frame Rate	30fps	
CAMERA	View Angle	H 85°±3°, V 53°±3°	
17379970900	Output Format	LVDS(POC)	
	Power	DC 8V(±0.5V)	
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CATEGORY	ITEM	SPECIFICATION	
	Fov	192° (H)	
AHN	Pixel Resolution	1280* 720P @30fps	
CAMERA	Video Output	AHD	
	Approach	Rear view monitoring	
	Fov	192° (H), 120° (V)	
LVDS	Pixel Resolution	1280 * 724P @30fps	
CAMERA	Video Output	LVDS (PoC)	
	Approach	SVM, Rear view	
	Fov	192° (H), 137° (V)	
ETHERNET	Pixel Resolution	1280 * 944P @30fps	
CAMERA	Video Output	Ethernet	
	Approach	SVM, Rear view	



Scenario 1. Loss the line marking on the road in reflected light

Scenario 2. Loss the line marking on the road in rainy weather



Conventional RGB camera

Polarized Camera







Conventional RGB camera

Polarized Camera





CATEGORY	ITEM	SPECIFICATION
	Image sensor	UHD CMOS
	Sensor Format	1/1.72 Inch
CAMERA	Resolution	3840 *2160P @30fps
	Pixel size	2.1µm
	FOV (H)	100°
	F no.	1.6
	Polarizer	4 in 1 method 4 polarization
	Application	Front camera

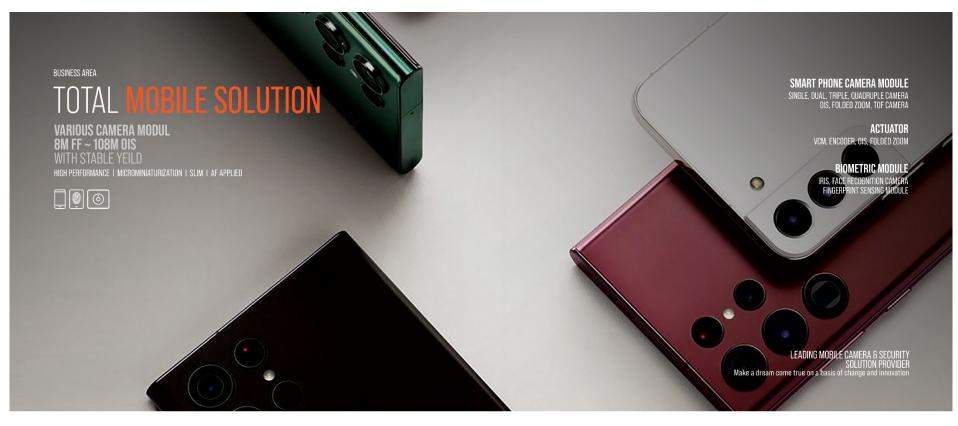








ITEM	FRONT CAMERA	REAR CAMERA
Image Sensor	QHD CMOS	QHD CMOS
Sensor Format	1/1.7 inch	1/1.7 inch
Resolution Driving	2560 *1440P @30fps	2560 *1440P @30fps
Resolution Parking	2560 *1440P @10fps	2560 *1440P @10fps
Pixel size	2.25µm	2.25µm
FOV(H)	100°	100°
F no.	1.6	1.6
Transmission	A-PHY(POC, UTP,STP)	A-PHY(POC, UTP,STP)
A-PHY IC	Valens VA7031	Valens VA7031
G-sensor	3-axis	*
MIC	Analog Microphone	-
Indicator LED	Blue	Blue



TOTAL MOBILE SOLUTION

SMART PHONE **CAMERA MODULE** SINGLE, DUAL, TRIPLE, QUADRUPLE CAMERA OIS, FOLDED ZOOM, TOF CAMERA

CAMERA MODULE LINE-UP_FIXED FOCUS MODEL

NEW TREND, ULTRA SLIM 10M FF ULTRA SLIM



8M FF	10M FF	10M FF	12M FF
12M FF	13M FF	13M FF	32M FF
	CORRECTION OF THE PARTY OF THE		TO SERVICE FOR SE



NEW TREND, ULTRA SLIM

CAMERA MODULE LINE-UP_AUTO FOCUS MODEL

48M AF 48M AF 50M AF

CAMERA MODULE LINE-UP_OIS MODEL

10M OIS	12M 0IS	12M OIS	48M 0IS
			Letting.
50M OIS	50M 0IS	64M DIS	108M OIS
	1000	(C)	-wa L

CAMERA MODULE LINE-UP_MULTI MODEL

64M AF / 12M AF

64M AF / 12M FF / 5M FF



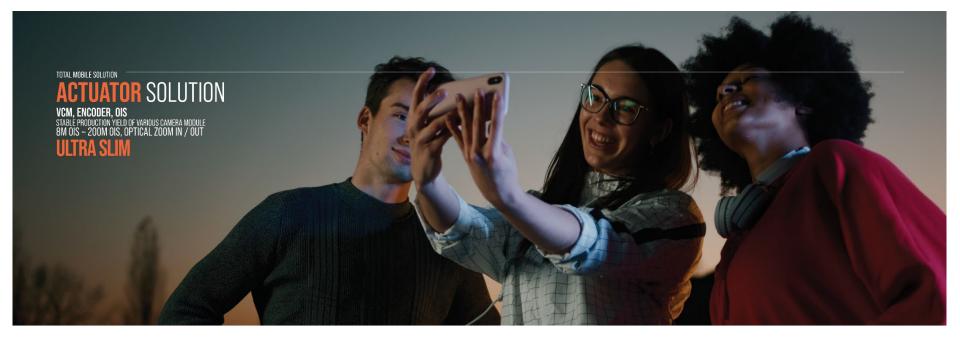


48M AF / 12M FF / 5M FF

24M AF / 10M FF / 8M FF / 5M FF

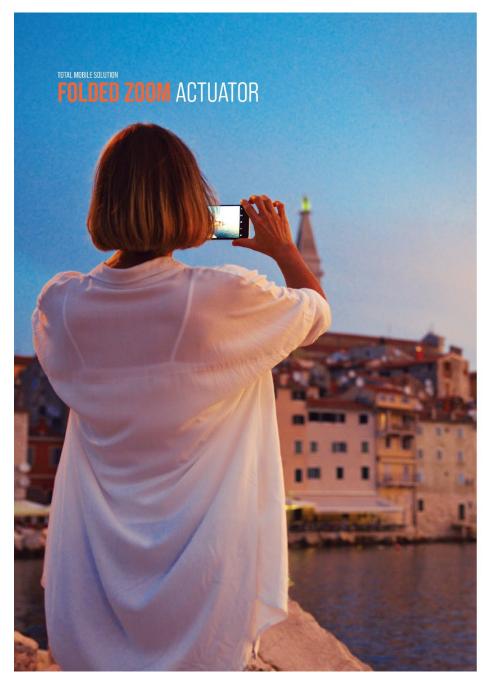






PRODUCT	TYPE	RESOLUTION	DIMENSION
	CVCA (BALL)	40M	9.1 X 9.74 / 3.76T
	OIS (BALL)	64M	13.7 X 13.1 / 4.65T
	OIS (BALL)	12M	13.7 X 13.1 / 4.65T
	OIS (BALL)	10M	11.1 X 11.1 / 5.65T
	OIS (BALL)	64M	13.5 X 13.5 / 4.8T
	OIS (BALL)	8M	10.0 X 10.0 / 4.3T
	OIS (BALL)	48M	12.5 X 12.1 / 4.3T
	OIS (BALL)	12M	11.3 X 11.7 / 3.95T
	OIS (BALL)	64M	13.5 X 13.5 / 4.8T

PRODUCT	TYPE	RESOLUTION	DIMENSION
	OIS (BALL)	50M	14.8 X 15.3 / 4.1T
	OIS (BALL)	12M 3X	11.1 X 11.1 / 4.8T
9	OIS (BALL)	108M	13.9 X 13.9 / 4.8T
	ZOOM (BALL)	12M 5X	36.2 X 14 / 6.2T
	OIS (BALL)	200M	18.0 X 18.7 / 4.9T
	ZOOM(BALL)	50M 10X	24.05 X 14.6 / 5.65T
	OIS(BALL)	50M	13.4 X 13.4 / 4.1T
	OIS(BALL)	200M	17.9 X 16.0 / 3.9T



FOLDED ZOOM ACTUATOR - 5X



- Up to X5 Optical Zoom-in
- Lower height using Prism mechanism
- Enhanced Image distortion as matching Pivot center and Optic center

AF SPEC

OIS SPEC

0. 20					
ITEM	UNIT	SPEC	ITEM	UNIT	SPEC
Rated Stroke	um	Min. 2520	Rated Stroke	Deg	X : Min. 5 (± 2.5)
Hysteresis	um	Max. 12	Rated Stroke	Deg.	Y: Min. 3 (± 1.5)
Linearity	um	Max. 20	Hysteresis	Deg.	Max. 0.10
Holding Current	mA	Max. 40	Linearity	Deg.	Max. 0.11
Actuating Tilt	Min	Max. 10	Max current	mA	Max. 100
₹6	353	(17)	Phase margin	Deg.	Min. 30
5 1	150	3073	Loop Gain	dB	Min. 20

FOLDED ZOOM ACTUATOR - 10X



- Up to X10 Optical Zoom-in
- Lower height using Prism mechanism
- Enhanced Image distortion as matching Pivot center and Optic center

AF SPEC

OIS SPEC

ITEM	UNIT	SPEC	ITEM	UNIT	SPEC
Rated Stroke	um	Min 2410	Rated Stroke	Deg	Min 2.4 (±1.2)
Hysteresis	um	Max 12	Hysteresis	Deg	Max 0.10
Linearity	um	Max 20	Linearity	Deg	Max 0.11
Holding Current	mA	Max 40	Max current	mA	Max 100
Actuating Tilt	Min	Max 10	Phase margin	Deg	Min 25
			Loop Gain	dB	Min 20

Tof CAMERA



Tof Camera Module

- Demonstration of the effective use of optical FOWLP in ToF sensor applications.
 A module that is 20% smaller and 230 µm thinner is achievable





SPECIFICATION

ITEM	MIN	NORMAL	MAX	UNIT	REMARK
PKG Height	222	270	318	UM	
Ball Pitch X	100	500	-	UM	
Ball Pitch Y	-	500	-	UM	
Total Ball Count	(%)	314		EA	
Resolution		320X240		PX	QVGA
Modulation Frequency of VCSEL Driver	20		100	MHZ	
VCSEL Wavelength		940		NM	

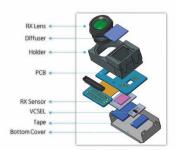
KEY FEATURES

Removal of PCB, substrate-less		
Size	3D stacking of ToF sensor and the driver IC	
	Thickness reduction more than 230um / Area reduction more than 20%	
Easy mounting	No Ceramic Carrier or substrate PCB needed	
Lasy mounting	Use ACF film or SMT process to electrically assemble the FOWLP onto the F-PCB	
Mass-production The optical FOWLP is fabricated by the wafer level process with mass- production capa		









SPECIFICATION

ITEM	SPEC	
Package Rx	S5K63DSX03-FGX9(S.LSI), 1/6.4", 3.5µm	
	BP_Filter: 3.37 x 2.81 x 0.21T,	
Bullion To	VCSEL	
Package Tx	Driver IC	
RF-PCB	6-2-6Layer RFPCB	
Capacitor	2.2uF, 10V	
	0.47uF, 6.3V	
	1uF, 10V	
	10k Ω	
Resister	2.2k Ω	
	100 Ω	
Connector	34Pin Header	
EEPROM	128Kbit	
Lens	5P, 85.1°(H) X 69.0°(V) / 98.9°(D)	
Housing	13.15 x 7.7 x 4.93T, M6.0xP0.25, SEA-20N	
Bottom COVER	13.15 x 7.55 x 2.87T, SUS316	
Diffuse(Flood)	90.6°(H) X 66.8°(V) / 4.5 x 4.9 x 0.3T	

KEY FEATURES

	Compact package size	Stacking internal components to reduce the module's overall area (About -20%)
Features	Compact package size	A slimmer module can be achieved due to reduction of Lens' thickness by 0.3mm
Higher bandwidth & Low heat	Noise reduction / Increase durability regarding high temperature	
	Mass Production & Low Cost	Ease securing capability for mass production Cost reduction

TOF CAMERA

ToF CAMERA





SPECIFICATION

ITEM	SPEC	
Package Rx	S5K63DSX03-FGX9(S.LSI), 1/6.4", 3.5μm	
	BP_Filter: 3.37 x 2.81 x 0.21T,	
	VCSEL	
Package Tx	Driver IC	
RF-PCB	6-2-6Layer RFPCB	
	2.2uF, 10V	
Capacitor	0.47uF, 6.3V	
	1uF, 10V	
	10k Ω	
Resister	2.2k Ω	
	100 Ω	
Connector	34Pin Header	
EEPROM	128Kbit	
Lens	4P, 77.8°(D)	
Housing	13.15 x 7.7 x 4.93T, M6.0xP0.25, SEA-20N	
Bottom COVER	13.15 x 7.55 x 2.87T, SUS316	
Diffuser(Flood)	3.12 x 3.5 x 0.3T	

KEY FEATURES

Features	Compact package size	A slimmer module can be achieved due to reduction of Lens' thickness by 0.3mm	
reatures	Mass Production & Low Cost	Ease securing capability for mass production Cost reduction	





SPECIFICATION

ITEM	SpEC	
Package Rx	S5K63DSX03-FGX9(S.LSI), 1/6.4", 3.5um	
	Milan (Flood)	
Package Rx	Trident (Spot)	
RF-PCB	6-2-6Layer RFPCB	
Driver IC	DW9916	
	2.2uF, 10V	
Package Rx	0.47uF, 6.3V	
achage IX	1uF, 10V	
	1nF, 10V	
	10k Ω	
Package Rx	2.2k Ω	
	100 Ω	
Connector	34Pin Header	
EEPROM	128Kbit	
Lens ass'y	4P, 100deg(H) X 83deg(V) / 121deg(D)	
Housing	16.6x10.75x5.25T, M6.5xP0.25, SEA-20N	
Band Pass Filter	7.1 x 7.1 x 0.21T	
Diffuser(near)	100deg(H) X 80deg(V) 3.3 X 2.6 X 0.85T	
Diffuser(far)	100deg(H) X 80deg(V) 3.7 X 2.6 X 0.8T	
MLA(near)	2.6 x 3.3 x 0.7T	
MLA(far)	2.6 × 3.7 × 0.7T	

KEY FEATURES

Features	Compact package size	A slimmer module can be achieved due to reduction of Lens' thickness by 0.3mm
	Mass Production & Low Cost	Ease securing capability for mass production Cost reduction

IMETRIC SENSING SOLUTION

FINGERPRINT SENSING MODULE

CAPACITANCE FINGERPRINT SENSING MODULE



SPECIAL COATING TECHNOLOGY (NON-SPRAY COATING)

WIRE BONDING TECHNOLOGY FOR LOW LOOP CONTROL

SPECIALIZED PROCESS FOR FINGERPRINT SENSOR MODULE
GREAT PACKAGE PROCESSING AND INTERNALIZED PACKAGE

CAPACITANCE LINE UP











OPTICAL FINGERPRINT SENSING MODULE



HIGH VISIVILITY BY IN-DISPLAY TYPE

INSTINTIVE USAGE (DIRECT TOUCH TYPE TO OLED PANEL)

HIGHER RESOLUTION THAN CAPACITANCE TYPE: 750 Dpi

NO EFFECT TO OLED YIELD BECAUSE MODULE IS NOT CONTACT TO A PANEL.

OPTICAL LINE UP











ULTRASONIC FINGERPRINT SENSING MODULE



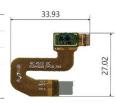
VERY THIN THICKNESS

FOD FINGER PRINT MODULE

ULTRASONIC TYPE

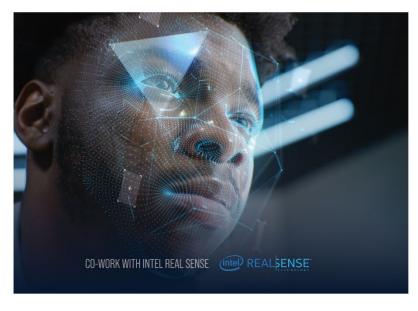
HIGH PERFORMANCE

	SPEC	
Operating temperature	-20°C ∽ 85°C	
Interface	SPI, VDD(3.3v),GND	
Module Size (mm)	33.93 x 27.02 x 0.137t(Sensor)	
Sensing Size (mm)	4.94 x 5.20	



FACE AUTHENTICATION SOLUTION





FEATURES

1:1M FAR (False Acceptance Rate)	Low cost design
Highly Secure : Encrypted feature points	Working in all lighting condition : indoor, outdoor, dark etc.
Strong anti-spoofing	Passed Google Certification Test
Vast and Unique 3D & 2D IR databases	

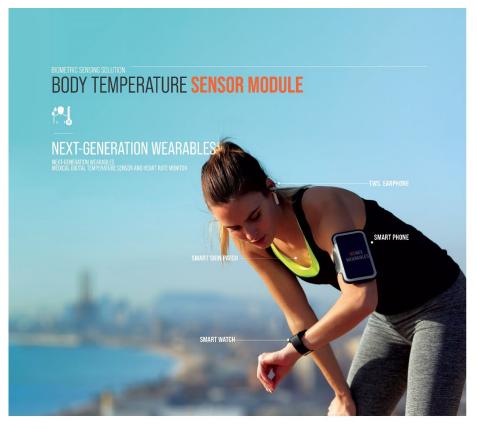
CURRENT PERFORMANCE	ITEM	CONDITION
Face Recognition: FAR 1:1M, TAR 99.41%, FRR 0.59%	SIZE(mm)	12.7 x 7.2 x 3.25t (Focus 60cm)
Anti Spoofing : SAR (Spoof Acceptance rate)< 1%	PIXEL	2M
Distance: Max 70cm	SENSOR	OV02A10 (1/5", 1.75μm)
	Field of View	85.2°
	F#	F2.0
	TTL	2.7mm



FEATURES	HIGH SECURITY / HIGH RECOGNITION RATE
Optimized Solution for "ALL EYE COLOR"	Unable to forge / falsify using photo, video, etc
Applied IR-LED & Band pass filter of 810nm wavelength range	Low rate of error recognition
Running VT / IRIS Camera via Switching function	Impossible to find same patterned iris
High recognition rate regardless of light from indoor-outdoor	After infancy, iris is no longer changed

SMART SECURITY





Very small size (for wearable)	Accurate non-contact temperature measurement
Health tracker	Optimization of space utilization

FEATURES

	· ·	
	SPEC	
CH / FOV	4 Cell / 70°	
Operating temperature	-20°C ~ 85°C	
Medical accuracy	Satisfied	
Interface	I2C, VDD(3.3v),GND	
Module Size (mm)	Size (mm) 5.20 x 13.32 x 1.78(t)	
Deco Size (mm)	4.20 x 4.32	



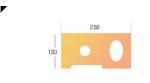
BIOMETRIC SENSING SOLUTION SKIN SENSOR



Very small size (for TWS)	SMD Type
Skin detector	Accurate skin contact / fabric contact detection

FEATURES

SPEC	,
2 Ch	
TBD	
I2C, VCC, GND	
2.50 x 1.50 x 0.80(t)	
	2 Ch TBD I2C, VCC, GND



PPG MODULE HEART PULSE. BODY FAT SENSOR MODULE

Heart Pulse, Oxygen Saturation, Body Fat	Module Type	
Optical, Impedance Type	1Ch ~ 8Ch Custom	

FEATURES

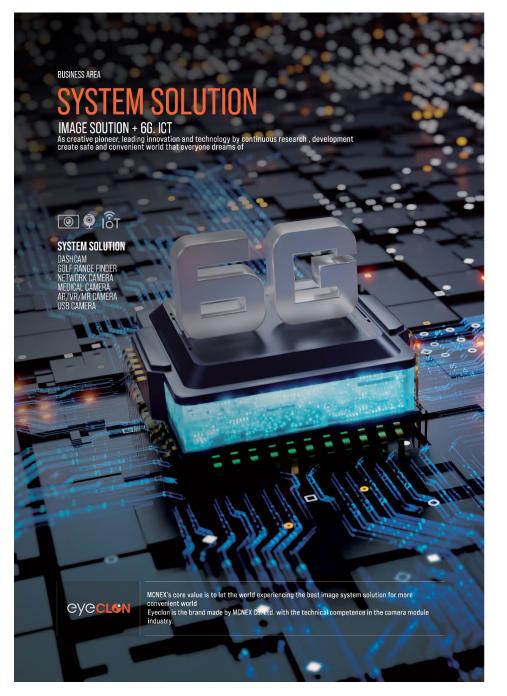
	SPEC	
PD CH	1Ch ~ 8 Ch	
LED	Green, Red, IR	
Operating temperature	-20℃ ~ + 60℃	
Interface	SPI/I2C, VCC, INT, GND	
Module Size (mm)	Design By Custom	







Model		MD-Q	
Resolution	92	Front: 2560x1440/Rear: 1920x1080(2ch)	
Image Sensor Rear		SC500AI / 135°(D) x 113°(H) x 61°(V) @30fps SC223A (1/2.8")/ 146°(D) x 116°(H) x 62°(V) @30fps	
LCD		2.0" TFT IPS LCD with Capacity Touch	
GNSS		Built in support(GPS,BEIDOU,QZSS)	
Memory Capacit	y	Micro SD Card up to 256GB	
Motion detection	n	3 Axis Acceleration Sensor & Radar Sensor	
Power		DC 12V/24V	
Operating Temp		-20°C ~ 60°C	
Dimension, weig	ht	56x42x29mm / 119g	
ADAS		LDWS, FCWS, FVSA	





DUAL CAMERA MODULE FOR AR&VR



Application	AR, VR, MR, XR	
Module Size	105mm x 10mm x 6.5mm	
Pixel Size	1/4" CSP	
Resolution	1 Mega pixel	
I/F	USB3.0 & MIPI	
F#	2.0	
View Angle	180°	
IR LED	850nm, 150°	

COMPACT/ENHANCED COVERAGE TOF CAMERAS FOR AR&VR



ITEM	SPEC		
Image Sensor	S5K63DSX03-FGX9(S.LSI), 1/6.4*, 3.5um		
Deckers Dv	Milan (Flood)		
Package Rx	Trident (Spot)		
RF-PCB	6-2-6Layer RFPCB		
Lens ass'y	4P, 100deg(H) X 83deg(V) / 121deg(D)		
Housing	16.6x10.75x5.25T, M6.5xP0.25, SEA-20N		
Band Pass Filter	7.1 x 7.1 x 0.21T		
DIFFUSER(near)	100deg(H) X 80deg(V) 3.3 X 2.6 X 0.85T		
DIFFUSER(far)	100deg(H) X 80deg(V) 3.7 X 2.6 X 0.8T		
MLA(near)	2.6 x 3.3 x 0.7T		
MLA(far)	2.6 x 3.7 x 0.7T		

ULTRA SLIM & ULTRA WIDE CAMERA FOR AR &VR



ITEM	SPEC	
	7.95 x 8.55 x 1.97T(Holder Top)	
Module Size	7.95 x 8.55 x 3.19T(Lens Top)	
Sensor	IMX825-AQ2H5-S(SONY) 1/3.19". 0.13T	
Lens	M5.5 x 0.2P, F.2.2, 120°	
Holder	7.95 x 8.55 x 1.75T, M5.5 x 0.2P	
RCF	NJS-201, 5.53 x 4.72 x 0.11T	
СВ	4-2-4 Layer PCB	
Connector	KN69B06-26DP_2-0.35V, 26Pin	
EEPROM	M24C64X-FCU6T/TF, 64kbits	

SMART GLASSES



HIGHLY SIMPLIFIED OPTIC STRUCTURE TO ENSURE

- 1. High efficiency of image data transmitting
- 2. Unique system lens to deliver 2D and 3D images
- 3. Lighter and smaller smart glass device

CENTER-MOUNTED OPTIC MODULE TO PROVIDE

- 1. Wider view angle compared to side-mounted ones
- 2. Unique system lens to deliver 2D and 3D images
- 3. Fit in any stylish design for any application

CENTER-MOUNTED OPTIC MODULE

Our center-mounted optic module enables wide view angle for our glasses, solving one of the most difficult challenges faced by other smart glasses

Center-mounted optic module also allows us to design our glasses more stylish, compared to other models that are bulky and inconvenient to handle

BEST-IN-CLASS OPTIC DESIGN

Our patented technology enables us to use extremely thin beam splitter (2mm) as part of the optic module, making our glasses light weight and more comfortable to wear

Even with our minimum-sized optic module, the virtual images are created far enough from your eyes which makes refocusing of your eyesight unnecessary in order to view images

SMART MEDIA



IOT. ICT
CONVERGENCE OF IMAGE SOLUTION AND ICT TECHNOLOGY

INFORMATION COLLECTION

Gender, Age, number of visitors, Preference, purchase pattern, etc

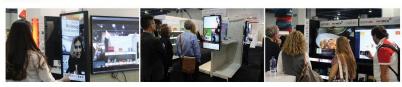
INFORMATION ANALYSIS

Log server save, report date collection, data extraction

INFORMATION SEND

Emergency prevention, translating service, purchase service, visitor data, sales data provide, security, control, suggested service

SMART DID | CES BOOTH IN 2019



USB CAMERA MODULE

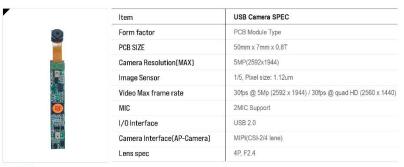


8MP UHD 120° USB CAMERA BOARD

	Item	USB Camera SPEC
	Form factor	PCB Module Type
_	PCB SIZE	40mm x 15mm x1.0T
	Camera Resolution[MAX]	8MP(3264x2448)
	Image Sensor	1/4, Pixel size: 1.12um
200 to 20		MJPEG: 8MP 30fps @(3264x2448), 4:3,
		5MP 30fps @(2592x1944)
	Video Max frame rate	Full HD 60fps@(1920x1080) / 2MP 60fps @(1600x1200)
50 8886 21141-1		HD(1280x720) 120fps, VGA(640x480) 120fps
100 B	MIC	Option
4	I/O Interface	USB 2.0
	Camera Interface(AP-Camera)	MIPI(CSI-2/4 lane)
	Lens spec	4P. F2.2

Application: Smart TV, USB Laptop, Tablet PC, Robot Vaccum Cleaner, Monitor, etc.

5MP USB CAMERA BOARD



Application: Smart TV, USB Laptop, Tablet PC, Robot Vaccum Cleaner, Monitor, etc.



8MP USB CAMERA BOARD

	Item	USB Camera SPEC
	Form factor	PCB Module Type
ĺ	PCB SIZE	40mm x 12mm x1.0T
	Camera Resolution(MAX)	8MP(3264x2448)
	Image Sensor	1/4, 200um, Pixel size: 1.12um
		MJPEG: 8MP 10fps @(3264x2448),4:3
	Video Max frame rate	5MP 10fps @(2592x1944)
		2MP 60fps @(1600x1200) / YUY2: 5fps @(1600x1200)
4	MIC	Option
	I/O Interface	USB 2.0
	Camera Interface(AP-Camera)	MIPI(CSI-2/4 lane)
	Lens spec	4P, F2.2

Application: Smart TV, USB Laptop, Tablet PC, Robot Vaccum Cleaner, Monitor, etc.



FEATURES	Item	Spec
High Quality Optical Lens(lens & Prism)	SIZE / Weight	107.35x38.17x69.03mm/T.B.D
Bright adjustable 2Color OLED(Red, Green)	Battery	CR2
Calculate a distance reflecting altitude as supporting Slope Mode	View LCD	2Color OLED
High Speed measuring distance	Range	0~1,200YD
Meter/Yard	Accuracy	0.3YD~0.5YD~1YD
High Accuracy	Speed (sec)	0.15~0.35~0.55
Water&dust proof: IP54	Optic zoom	X6
CR2 Battery(Replaceable)	FOV	7°
Anti-hand shaking(Pin seeker , Jolt)	Water/dust proof	IPX54
Slope mode/non slope mode/scan mode	Slope Mode	Support
Indicator LED(Slope mode: LED On)	Operating Temp.	-20°C ~ 50°C

FEATURES	Item		Spec	
Measure a distance to a green hall by voice command	SIZE		Ф44~Ф35, 12.4mm(H)	
Support multi satellite system, Gain over 24 satellites	Weight		22.5g	
Map update through Blue Tooth	GPS		GPS, GLONASS, QZSS, BEIDOU	
Calculate a distance reflecting altitude	Voice recognition		O ("Hi-Alice")	
Meter/Yard	BlueTooth		O (BLE 5.1)	
Measure a ball travel distance (Long Key)	Battery		Chargeable Lithium Polymer	
Setting menu on a smart phone by app.	Charging type		Pogo Cable 4pin	
Auto detect a golf course and hall	Operating time at full charging		10hr~	
Select a green (left green/right green/both)	Trigger type for distance Guide		Voice command or Button	
Support Pogo charging port(Magnetic pogo type)	I/F	Wireless	Blue Tooth	
		Cable	USB	





MANUFACTURING SITE	Phuc Son Industrial Park, Ninh Binh City, Vietnam				
FACTORY SIZE	Land Area		Building Area	Employees	
TAOTOTT SIZE	150,00	10 m²	127,338 m²	6,124	
ITEM & CAPACITY	<u>*</u>	0			
	Mobile Camera	Actuator	Biometric	Automotive Camera	
	30M / Month	11M / Month	9M / Month	1.5M / Month	







3TH FACTORY TOTAL AREA 24,000 m²

2 FLOOR - 12,000 m²

3 FLOOR - 12,000 m²

DEM. ODM. EMS

COMPETITIVENESS



Robust quality management system established through co-work with SAMSUNG, HKMC, Japan & US Customer + HKMC 5 Star (Quality system)

FACTORY SYSTEM. ERP. MES. PLM SYSTEM FULLY ESTABLISHED.







ERP (Enterprise Resource Planning) MES (Manufacturing Execution System) PLM (Product Lifecycle Management)

OHSAS18001

FACTORY CERTIFICATES

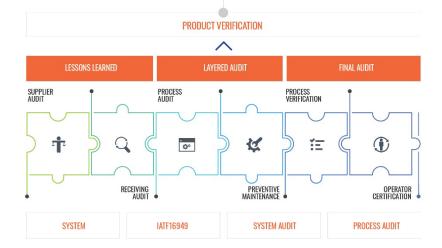
IATF16949

ISO14001

ISO45001

ISO26262

DEVELOPMENT / PRODUCTION QUALITY MANAGEMENT PROCESS



GLOBAL NETWORK - ON-TIME DELIVERY



Factory/R&D	Korea(Seoul), Vietnam(Hanoi)				
Sales office	Korea(Seoul), Vietnam(Hanoi), China(Shanghai), Japan, Taiwan				
Cost competitiveness	Factory located in bonded area	Standard laboring days in Vietnam : 6days a week & Low laboring cost			
Labor friendly factory environment	No laboring dispute since establishment of Vietnam Factory [2013 ~ now]				
	"Excellent enterprise award for labor environment"		MES System		
Logistics advantages	Through FTA, can be shipped any country without worrying (US / CN / EU / AU / Pacific, etc.)				
	Vietnam-US tariff agreement -> (Cheap tariff due to TPP contract)				
	Fast custom clearance : 1~2days earlier custom clearance than others(Factory located in bonded area)				

Enough space in MCNEX's 3rd Vietnam Factory for "New project & New customer"

VARIOUS EXPERIENCE OF IMAGE SOLUTION TECHNOLOGY

Co-work with HKMC for ADAS camera system

Co-work with Microsoft for stereo camera development for AR, VR application

Selected as a standard module of iris recognition camera system into Qualcomm AP chip

Development of camera system for ADAS application with TI, NXP & Socio Next AP

Co-develop with Corephotonics for front camera

Camera module development for Autonomous driving level 3 / Level 4

18 years of experience in the field of camera module: Single / Dual / Tri-Focal / Quadruple

Abundant experience of government project for advanced technology